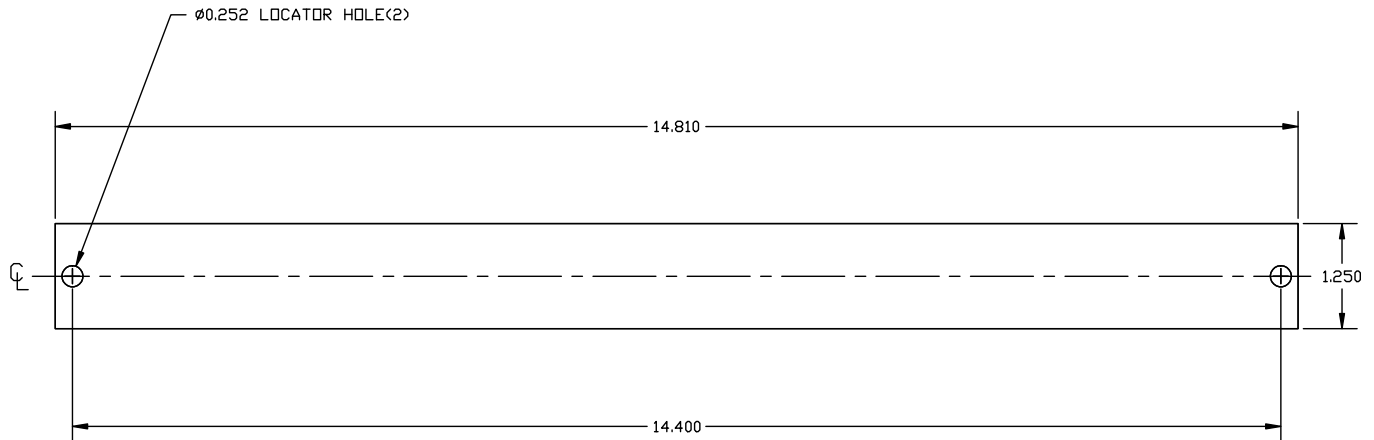


Blind Embossing and Die Cutting

Die Perimeter/Alignment Hole Specifications



Die Perimeter/Alignment Hole Specifications

Drawing above shows the blind embossing and die cutting die perimeter and alignment hole specifications. These specifications match the tooling station chase. Perimeter and alignment hole specifications are critical.

Blind Embossing Die Specifications

Die: Photo Etched Magnezium, 16 Gauge (.064"/1.63mm) thick.
Counter: Molded on Fiberglass Base, (.017"/.4318mm) base thickness.
Counter Mounting Tape: TST-1.25 (1.25" x 177" roll) double sided tape.
Note: Counter base thickness must not exceed specifications.
Blind embossing dies can be mounted on a common chase.
The blind embossing chase can also be used for strike perforating.

Flexible Die Cutting Die Specifications

Die: .040"/1mm thick maximum thickness.
.008"/.010" base thickness after etching.
60 degree blade angle
Note: Flexible die cutting dies require a mounting chase with ejector pin pattern matching on chase and die.